

OptiMOS™ Power-Transistor

Feature

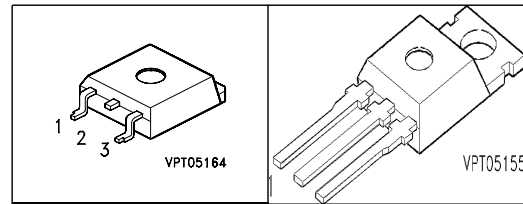
- N-Channel
- Enhancement mode
- 175°C operating temperature
- Avalanche rated
- dv/dt rated

Product Summary

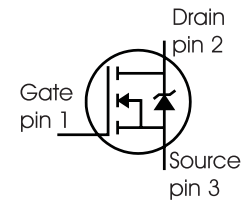
V_{DS}	30	V
$R_{DS(on)}$ max. SMD version	3.1	mΩ
I_D	80	A

P-TO263-3-2

P-TO220-3-1



Type	Package	Ordering Code	Marking
SPP80N03S2-03	P-TO220-3-1	Q67040-S4247	2N0303
SPB80N03S2-03	P-TO263-3-2	Q67040-S4258	2N0303



Maximum Ratings, at $T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Value	Unit
Continuous drain current $T_C = 25\text{ °C}$, ¹⁾ $T_C = 100\text{ °C}$	I_D	80 80	A
Pulsed drain current $T_C = 25\text{ °C}$	I_D puls	320	
Avalanche energy, single pulse $I_D = 80\text{ A}$, $V_{DD} = 25\text{ V}$, $R_{GS} = 25\text{ Ω}$	E_{AS}	810	mJ
Reverse diode dv/dt $I_S = 80\text{ A}$, $V_{DS} = 24\text{ V}$, $di/dt = 200\text{ A/μs}$, $T_{jmax} = 175\text{ °C}$	dv/dt	6	kV/μs
Gate source voltage	V_{GS}	±20	V
Power dissipation $T_C = 25\text{ °C}$	P_{tot}	300	W
Operating and storage temperature	T_j , T_{stg}	-55... +175	°C
IEC climatic category; DIN IEC 68-1		55/175/56	

Thermal Characteristics

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Characteristics					
Thermal resistance, junction - case	R_{thJC}	-	-	0.5	K/W
Thermal resistance, junction - ambient, leaded	R_{thJA}	-	-	62	
SMD version, device on PCB: @ min. footprint @ 6 cm ² cooling area ²⁾	R_{thJA}	-	-	62 40	

Electrical Characteristics, at $T_j = 25\text{ }^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Static Characteristics					
Drain-source breakdown voltage $V_{GS}=0V, I_D=1mA$	$V_{(BR)DSS}$	30	-	-	V
Gate threshold voltage, $V_{GS} = V_{DS}$ $I_D=250\mu A$	$V_{GS(th)}$	2.1	3	4	
Zero gate voltage drain current $V_{DS}=30V, V_{GS}=0V, T_j=25^\circ C$ $V_{DS}=30V, V_{GS}=0V, T_j=125^\circ C$	I_{DSS}	-	0.01 1	1 100	μA
Gate-source leakage current $V_{GS}=20V, V_{DS}=0V$	I_{GSS}	-	1	100	nA
Drain-source on-state resistance ³⁾ $V_{GS}=10V, I_D=80A$ $V_{GS}=10V, I_D=80A, \text{SMD version}$	$R_{DS(on)}$	-	2.6 2.3	3.4 3.1	m Ω

¹Current limited by bondwire; with a $R_{thJC} = 0.5\text{ K/W}$ the chip is able to carry $I_D = 230A$ and calculated with max. source pin temperature of $85^\circ C$.

²Device on $40mm \times 40mm \times 1.5mm$ epoxy PCB FR4 with 6 cm^2 (one layer, $70\text{ }\mu m$ thick) copper area for drain connection. PCB is vertical without blown air.

³Diagrams are related to straight lead versions

Electrical Characteristics, at $T_j = 25\text{ }^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

Dynamic Characteristics

Transconductance	g_{fs}	$V_{DS} \geq 2 \cdot I_D \cdot R_{DS(on)max}$, $I_D = 80\text{A}$	66	132	-	S
Input capacitance	C_{iss}	$V_{GS} = 0\text{V}$, $V_{DS} = 25\text{V}$, $f = 1\text{MHz}$	-	5160	6450	pF
Output capacitance	C_{oss}		-	2400	3000	
Reverse transfer capacitance	C_{rss}		-	410	615	
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 15\text{V}$, $V_{GS} = 10\text{V}$, $I_D = 80\text{A}$, $R_G = 2.2\Omega$	-	22	33	ns
Rise time	t_r		-	325	490	
Turn-off delay time	$t_{d(off)}$		-	90	140	
Fall time	t_f		-	110	160	

Gate Charge Characteristics

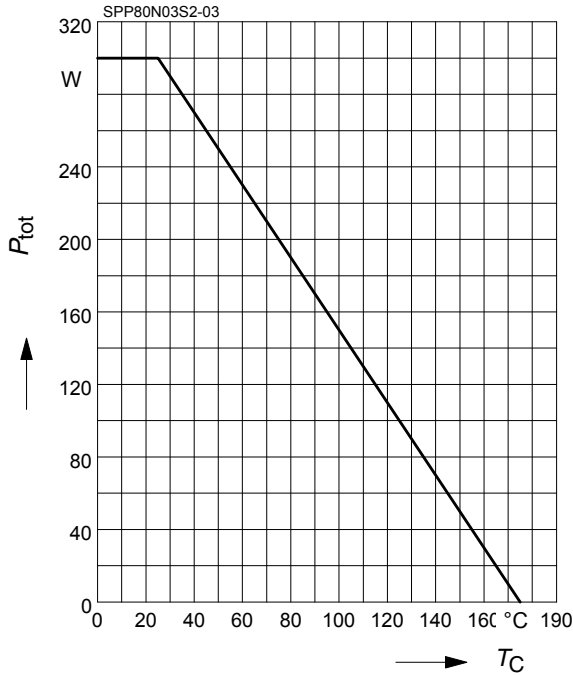
Gate to source charge	Q_{gs}	$V_{DD} = 24\text{V}$, $I_D = 80\text{A}$	-	25	30	nC
Gate to drain charge	Q_{gd}		-	32	48	
Gate charge total	Q_g	$V_{DD} = 24\text{V}$, $I_D = 80\text{A}$, $V_{GS} = 0$ to 10V	-	110	140	
Gate plateau voltage	$V_{(plateau)}$	$V_{DD} = 24\text{V}$, $I_D = 80\text{A}$	-	5.2	-	V

Reverse Diode

Inverse diode continuous forward current	I_S	$T_C = 25\text{ }^\circ\text{C}$	-	-	80	A
Inverse diode direct current, pulsed	I_{SM}		-	-	320	
Inverse diode forward voltage	V_{SD}	$V_{GS} = 0\text{V}$, $I_F = 80\text{A}$	-	0.9	1.3	V
Reverse recovery time	t_{rr}	$V_R = 15\text{V}$, $I_F = I_S$, $di_F/dt = 100\text{A}/\mu\text{s}$	-	53	66	ns
Reverse recovery charge	Q_{rr}		-	77	96	nC

1 Power dissipation

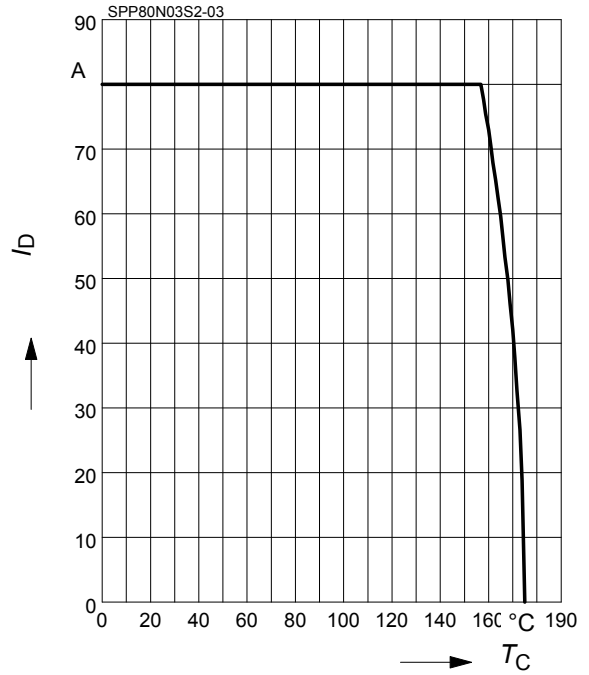
$$P_{tot} = f(T_C)$$



2 Drain current

$$I_D = f(T_C)$$

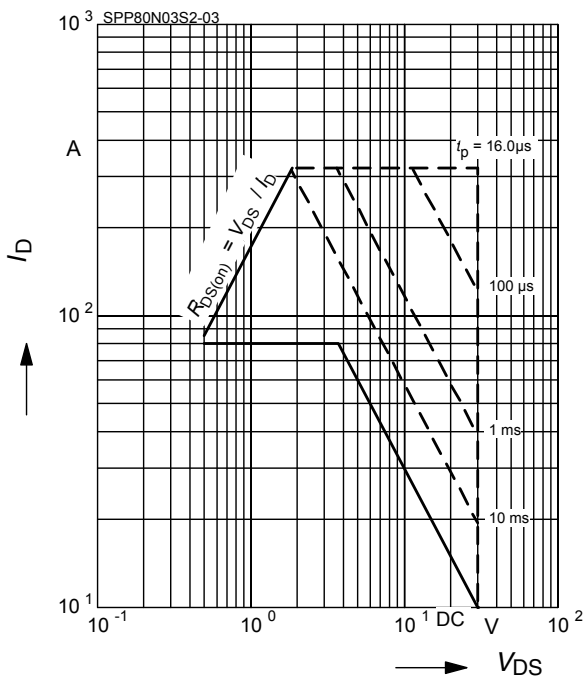
parameter: $V_{GS} \geq 10 \text{ V}$



3 Safe operating area

$$I_D = f(V_{DS})$$

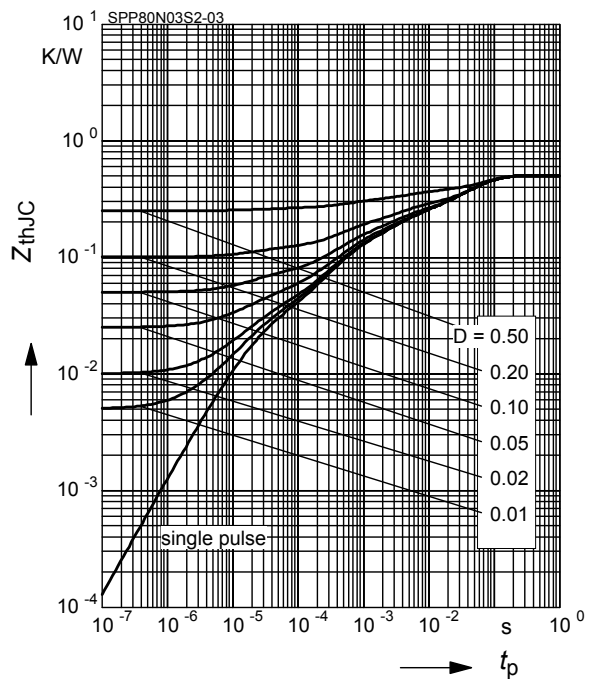
parameter: $D = 0$, $T_C = 25 \text{ °C}$



4 Transient thermal impedance

$$Z_{thJC} = f(t_p)$$

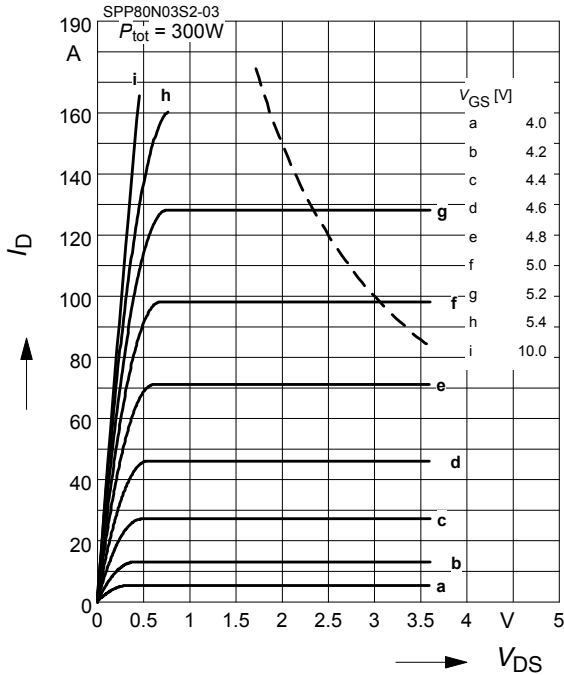
parameter: $D = t_p/T$



5 Typ. output characteristic

$I_D = f(V_{DS}); T_j = 25^\circ\text{C}$

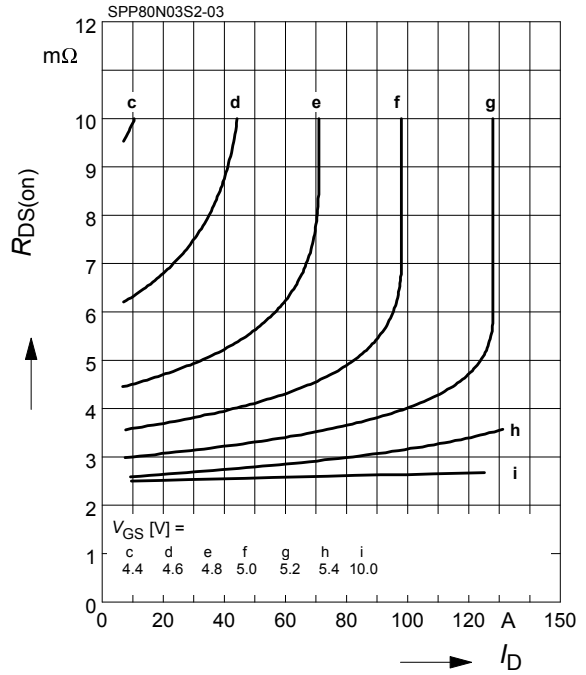
parameter: $t_p = 80 \mu\text{s}$



6 Typ. drain-source on resistance

$R_{DS(on)} = f(I_D)$

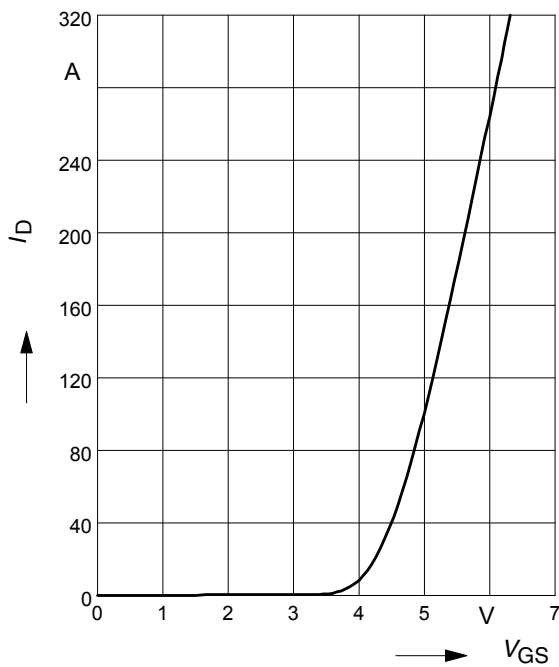
parameter: V_{GS}



7 Typ. transfer characteristics

$I_D = f(V_{GS}); V_{DS} \geq 2 \times I_D \times R_{DS(on)max}$

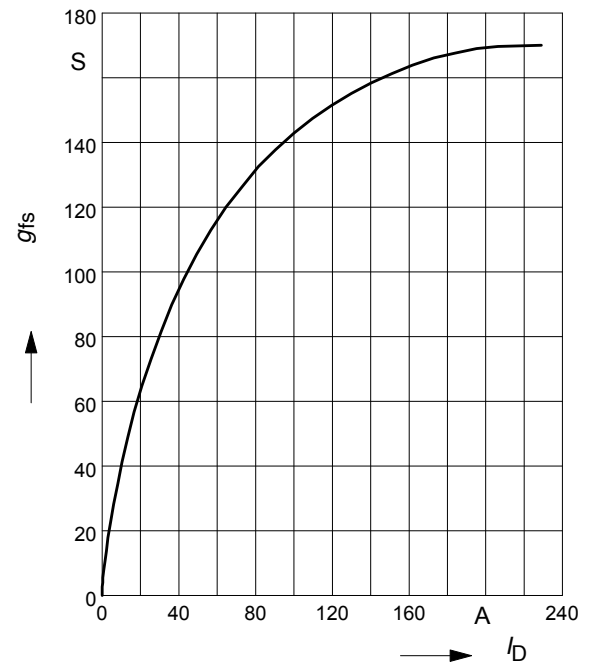
parameter: $t_p = 80 \mu\text{s}$



8 Typ. forward transconductance

$g_{fs} = f(I_D); T_j = 25^\circ\text{C}$

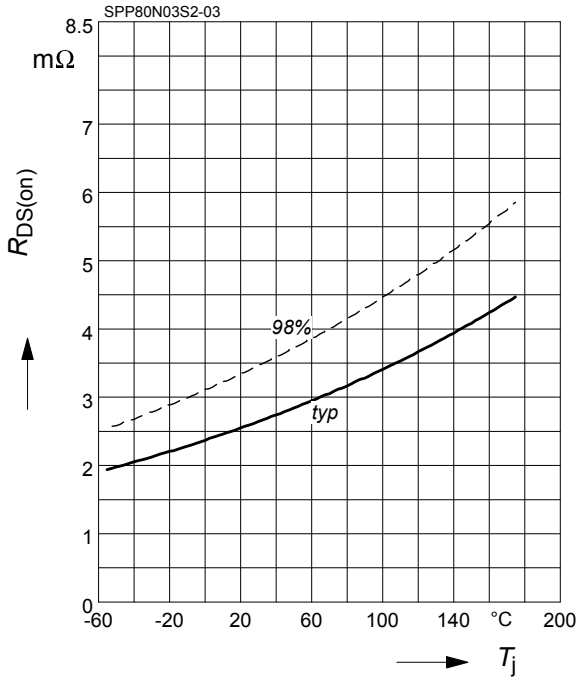
parameter: g_{fs}



9 Drain-source on-state resistance

$$R_{DS(on)} = f(T_j)$$

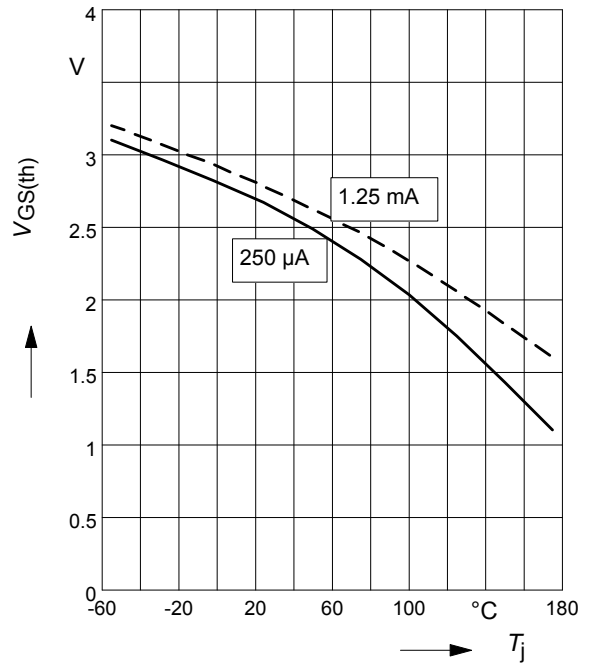
parameter: $I_D = 80\text{ A}$, $V_{GS} = 10\text{ V}$



10 Typ. gate threshold voltage

$$V_{GS(th)} = f(T_j)$$

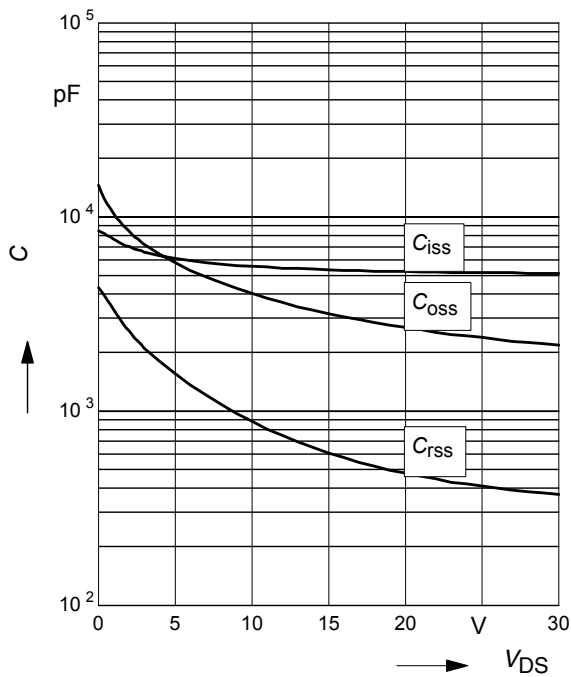
parameter: $V_{GS} = V_{DS}$



11 Typ. capacitances

$$C = f(V_{DS})$$

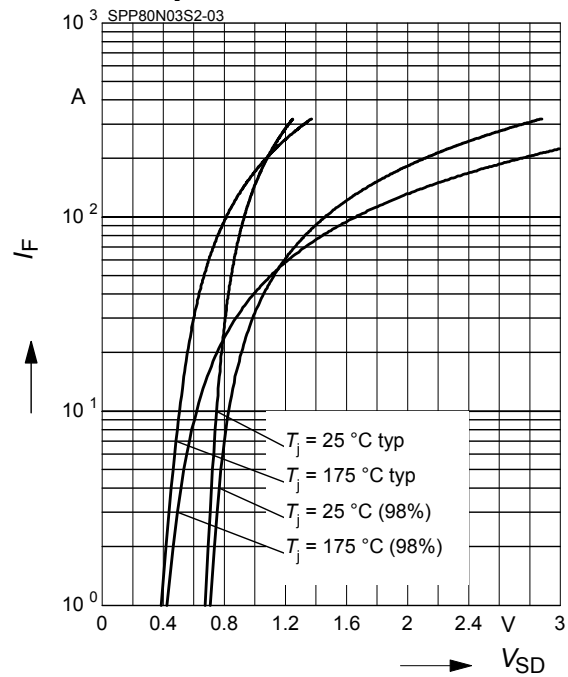
parameter: $V_{GS}=0\text{V}$, $f=1\text{ MHz}$



12 Forward character. of reverse diode

$$I_F = f(V_{SD})$$

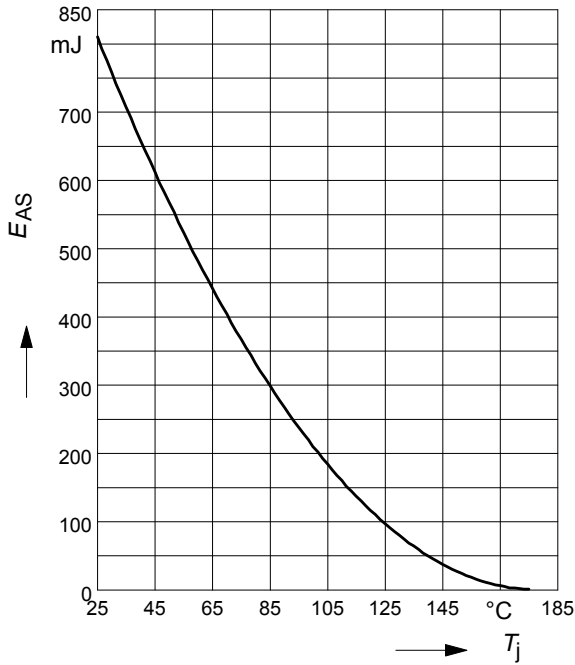
parameter: T_j , $t_p = 80\text{ μs}$



13 Typ. avalanche energy

$$E_{AS} = f(T_j)$$

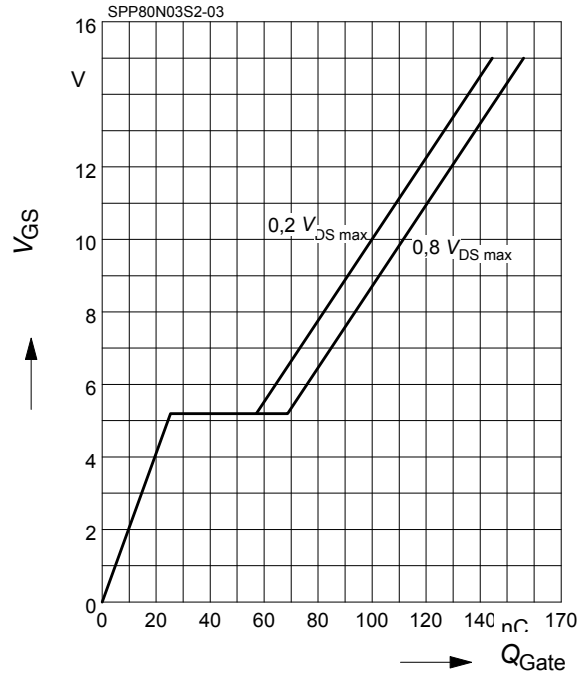
par.: $I_D = 80 \text{ A}$, $V_{DD} = 25 \text{ V}$, $R_{GS} = 25 \Omega$



14 Typ. gate charge

$$V_{GS} = f(Q_{Gate})$$

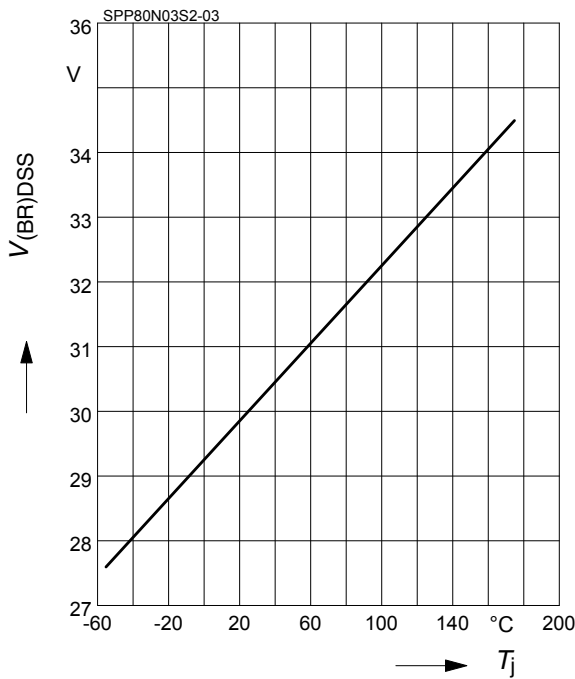
parameter: $I_D = 80 \text{ A}$ pulsed



15 Drain-source breakdown voltage

$$V_{(BR)DSS} = f(T_j)$$

parameter: $I_D = 10 \text{ mA}$



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